Ministério do Meio Ambiente
Instituto Brasileiro do Meio Ambiente e dos Recursos Naturais Renováveis

CADASTROS TÉCNICOS FEDERAIS
CONSULTA PÚBLICA A CERTIFICADO DE REGULARIDADE - CR

Registro n.º: 5283519 Data da consulta: 10/06/2025 CR emitido em: 09/06/2025 CR válido até: 09/09/2025

Dados básicos

CNPJ: 07.275.920/0001-61
Razão social: LENOVO TECNOLOGIA (BRASIL) LTDA
Nome fantasia: LENOVO TECNOLOGIA (BRASIL) LTDA
Data de abertura: 03/03/2005

Endereço

Logradouro: ESTM JOSE COSTA DE MESQUITA
Complemento: MOD 5 A 10
N.º: 200
Municipio: INDAIATUBA
Bairro: CHACARA ALVORADA
UF: SP
CEP: 13337-200

Cadastro Técnico Federal de Atividades Potencialmente Poluidoras e Utilizadoras de Recursos Ambientais – CTF/APP

Categoria	Detalhe
5 - Indústria de material Elétrico, Eletrônico e Comunicações	2 - Fabricação de material elétrico, eletrônico e equipamentos para telecomunicação e informática

Conforme dados disponíveis na presente data, a pessoa jurídica acima possui Certificado de Regularidade em conformidade com as obrigações cadastrais e de prestação de informações ambientais sobre as atividades desenvolvidas sob controle e fiscalização do Ibama, por meio do CTF/APP.

O certificado de regularidade emitido pelo CTF/APP não desobriga a pessoa inscrita de obter licenças, autorizações, permissões, concessões, alvarás e demais documentos exigíveis por instituições federais, estaduais, distritais ou municipais para o exercício de suas atividades.

O Certificado de Regularidade do CTF/APP não habilita o transporte e produtos e subprodutos florestais e faunísticos.

Cadastro Técnico Federal de Atividades e Instrumentos de Defesa Ambiental - CTF/AIDA

Código	Atividade
0005-40	Gerenciamento de resíduos perigosos - armazenamento de resíduos perigosos - Lei nº 12.305/2010
0005-10	Gerenciamento de resíduos perigosos - geração de resíduos perigosos - Lei nº 12.305/2010
0004-00	Gerenciamento de resíduos sólidos não perigosos - Lei nº 12.305/2010

Conforme dados disponíveis na presente data, a pessoa jurídica acima possui Certificado de Regularidade, em conformidade com as obrigações cadastrais do CTF/AIDA.

A inscrição no CTF/AIDA constitui declaração, pela pessoa jurídica, de observância dos padrões técnicos normativos estabelecidos pela Associação Brasileira de Normas Técnicas – ABNT, pelo Instituto Nacional de Metrologia, Qualidade e Tecnologia – INMETRO e pelo Conselho Nacional de Meio Ambiente - CONAMA.

O Certificado de Regularidade emitido pelo CTF/AIDA não desobriga a pessoa inscrita de obter licenças, autorizações, permissões, concessões, alvarás e demais documentos exigíveis por instituições federais, estaduais, distritais ou municipais para o exercício de suas atividades, especialmente os documentos de responsabilidade técnica, qualquer o tipo e conforme regulamentação do respectivo Conselho de Fiscalização Profissional, quando exigíveis.

O Certificado de Regularidade no CTF/AIDA não produz qualquer efeito quanto à qualificação e à habilitação técnica da pessoa jurídica inscrita.

Fechar

DATE: May 17, 2012

SUBJECT: **Lenovo's Progress on RoHS**

Lenovo is committed to the environment. An important priority for Lenovo was the implementation of RoHS (Restriction of Hazardous Substances) requirements globally. Lenovo has met all the RoHS requirements currently in effect, most well in advance of their implementation dates.

- Lenovo products sold in the European Union and Japan, on or after July 1, 2006, meet the requirements of the European Union Directive 2002/95/EC (RoHS).
- Lenovo products sold in Japan, on or after July 1, 2006, meet the requirements of J-Moss ("Japan RoHS").
- Lenovo products sold in California, on or after January 1, 2007, meet the requirements of "California's RoHS" (SB 20, 50).
- Lenovo products sold in the People's Republic of China, on or after March 1, 2007, meet the requirements of "Management Methods for Control of Pollution from Electronic Information Products" ("China RoHS").
- Lenovo products sold in South-Korea, on or after January 1, 2008, meet the requirements of "South Korea's equivalent of EU RoHS, WEEE and End of Life Vehicle (ELV) Directives" ("South-Korea RoHS").
- Lenovo products sold to the New York City government, on or after March 1, 2007, meet the requirements of the City's environmental preferred purchasing regulations.
- Lenovo products sold in Turkey, on or after June 1, 2009, meet the requirements of the Republic of Turkey Directive on the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (EEE) ("Turkey RoHS").
- Lenovo products sold in Ukraine, on or after January 1, 2011, meet the requirements of the Technical Directive on Restriction of Hazardous Substances in Electric and Electronic Equipment enforced by the Government, Decision № 1057 dated 2008/12/03" ("Ukraine TR on RoHS").
- Lenovo products sold in India, on or after May 1, 2012, meet the requirements of the India E-waste (Management and Handling) rules, 2011. ("India RoHS")

Lenovo complies with RoHS requirements in each geography and country in which our products are sold worldwide.

Rob J Taylor - Director of Environmental Affairs,
Corporate Quality Programs, Safety and Standards
5A6 / Building 2
1009 Think Place
Morrisville, NC 27560 USA

Ref. Certif. No.

DK-149264-UL

IEC SYSTEM FOR MUTUAL RECOGNITION OF TEST CERTIFICATES FOR ELECTRICAL EQUIPMENT (IECEE) CB SCHEME

CB TEST CERTIFICATE

Product	Notebook Computer
Name and address of the applicant	Lenovo Japan LLC MINATOMIRAI CENTER BLDG 21F 3-6-1 MINATOMIRAI NISHI-KU YOKOHAMA-SHI, Kanagawa, 220-0012 Japan
Name and address of the manufacturer	Lenovo PC HK Limited 23/F, Lincoln House, Taikoo Place, 979 King's Road, Quarry Bay,Hong Kong, P.R.China
Name and address of the factory Note: *When more than one factory, please report on page 2*	LCFC (HeFei) Electronics Technology Co., Ltd No. 3188-1 Yungu Road (Comprehensive Bonded Zone), Hefei Economic & Technological Development Area, HEFEI ANHUI 230601, China ☒ Additional Information on page 2 and page 3
Ratings and principal characteristics	(optional) 20Vdc, 3.25A
Trademark / Brand (if any)	Lenovo
Customer's Testing Facility (CTF) Stage used	
Model / Type Ref.	TP00148Dxxxxxxxx, ThinkPad E14 Gen 6xxxxxxxx, 21M3xxxxxxxx, 21M4xxxxxxxx ☒ Additional Information on page 3
Additional information (if necessary may also be reported on page 2)	**Additionally evaluated to:** EN IEC 62368-1:2020, EN IEC 62368-1:2020/A11:2020 National Differences: AU, CA, CN, EU Group Differences, JP, NZ, SA, SG, US ☐ Additional Information on page 2
A sample of the product was tested and found to be in conformity with	IEC 62368-1:2018
As shown in the Test Report Ref. No. which forms part of this Certificate	E302338-A7135-CB-1 issued on 2024-01-08

This CB Test Certificate is issued by the National Certification Body

UL Solutions

☐ UL Solutions (US), 333 Pfingsten Rd IL 60062, Northbrook, USA
☒ UL Solutions (Demko), Borupvang 5A DK-2750 Ballerup, DENMARK
☐ UL Solutions (JP), Marunouchi Trust Tower Main Building 6F, 1-8-3 Marunouchi, Chiyoda-ku, Tokyo 100-0005, JAPAN
☐ UL Solutions (CA), 7 Underwriters Road, Toronto, M1R 3B4 Ontario, CANADA

For full legal entity names see www.ul.com/ncbnames

Date: 2024-01-09

Signature: Thomas Wilson

Ref. Certif. No.

DK-149264-UL

Factory(ies):
Lenovo (India) Private Limited
19/1A & 19/2A, CUDDALORE MAIN ROAD,
EDAYARPALAYAM VILLAGE, THAVALAKUPPAM
PUDUCHERRY -605007
India

Lenovo (Shanghai) Electronics Technology Co., Ltd.
Section 304-305, Building No. 4, # 222, Meiyue Road,
China (Shanghai) Pilot Free Trade Zone, Shanghai
200131,
China

Lenovo US Fulfillment Center L L C
6540 Franz Warner Parkway Whitsett, NC 27377,
United States of America

NEC Personal Computers, Ltd
6-80, Shimohanazawa 2-Chome,Yonezawa-shi,
Yamagata 992-8520,
Japan

LENOVO INFORMATION PRODUCTS (SHENZHEN) CO., LTD
2F, NO.1 Plant , Lenovo Innovation Park, Lidu Road, Loucun Community, Xinhu Street, Guangming District ,
Shenzhen, Guangdong,
China

PLANT 2 - SANSEI
EVA PERÓN 97 - USHUAIA - NOBLEX S.A, TIERRA
DEL FUEGO,
Argentina

Lenovo Centro Tecnologico S de RL de CV
Apodaca Technology Park Boulevard Escobedo #316 Apodaca, Nuevo Leon, C.P. 66600.
Mexico

Lenovo Centro Tecnologico S de RL de CV
Boulevard Escobedo #318 Apodaca Technology Park,
CP 66627 APODACA NL,
Mexico

LENOVO TECNOLOGIA (BRASIL) LTDA
Estrada Municipal Jose Costa de Mesquita, 200, Modulos
5 a 10, Chacara Alvorada, INDAIATUBA SP 13337-200,
Brazil

Additional information (if necessary)

☐ UL Solutions (US), 333 Pfingsten Rd IL 60062, Northbrook, USA
☒ UL Solutions (Demko), Borupvang 5A DK-2750 Ballerup, DENMARK
☐ UL Solutions (JP), Marunouchi Trust Tower Main Building 6F, 1-8-3 Marunouchi, Chiyoda-ku, Tokyo 100-0005, JAPAN
☐ UL Solutions (CA), 7 Underwriters Road, Toronto, M1R 3B4 Ontario, CANADA

For full legal entity names see www.ul.com/ncbnames

Date: 2024-01-09

Signature:

Thomas Wilson

Ref. Certif. No.

DK-149264-UL

MOTOROLA (WUHAN) MOBILITY TECHNOLOGIES COMMUNICATION CO LTD
NO.19, Gaoxin 4Th Rd, East Lake High-Tech Zone, WUHAN HUBEI 430205
China

GUANGXI SANCHUANG TECHNOLOGY CO LTD
The Second Floor of Plant C01, Plant C02, Plant C03 and Plant D03 Guangxi Sannuo Smart Industrial Park, No.3, Gaoke Road, Beihai Industrial Park, BEIHAI GUANGXI
536000,
China

Hefei LCFC Electronics Trading Co.,Ltd.
The western part of 3rd Floor in Building B, Yunhai Road Industrial Park, No. 176，Yun'er Road, Hefei Economic and Technological Development Area, Hefei Anhui 230601,
China

Hefei Jingzhuo Photoelectric Co., Ltd.
The northern part of 1st Floor and the eastern part of 3rd Floor in Building B, Yunhai Road Industrial Park, No. 176, Yun'er Road, Hefei Economic Development Zone, Hefei Anhui 230601,
China

Additional Model Detail(s):
TP00148Dxxxxxxxx, ThinkPad E14 Gen 6xxxxxxxx, 21M3xxxxxxxx, 21M4xxxxxxxx, The "x" in the model name can be 0 to 9, A to Z, a to z, any symbol or blank for marketing use only

Additional information (if necessary)

☐ UL Solutions (US), 333 Pfingsten Rd IL 60062, Northbrook, USA
☒ UL Solutions (Demko), Borupvang 5A DK-2750 Ballerup, DENMARK
☐ UL Solutions (JP), Marunouchi Trust Tower Main Building 6F, 1-8-3 Marunouchi, Chiyoda-ku, Tokyo 100-0005, JAPAN
☐ UL Solutions (CA), 7 Underwriters Road, Toronto, M1R 3B4 Ontario, CANADA

For full legal entity names see www.ul.com/ncbnames

Date: 2024-01-09

Signature:

Thomas Wilson

MEMBERSHIP LIST

The UEFI Forum community of members is represented by industry-leading OEMs, IHVs, chip manufactures, BIOS and firmware vendors and operating system vendors.

PROMOTERS

AMD
American Megatrends, Inc.
Apple Inc.
ARM Limited
Dell
Hewlett Packard Enterprise
HP, Inc.
Insyde Software
Intel
Lenovo
Microsoft
Phoenix Technologies

CONTRIBUTORS

ZD Technology (Beijing) Co., Ltd. (Kunlun Technology (Beijing) Co., Ltd)
Absolute Software Corporation
Alibaba (China) Co., Ltd.
Ampere Computing LLC
ASMedia Technology Inc.
ASUSTeK COMPUTER INC.
Beijing Bytedance Network Technology Ltd.
Broadcom Corporation
Canonical Limited
Cirrus Logic, Inc.
Cisco
Citrix Systems, Inc.
Cumulus Networks Inc.
Daten Tecnologia
Dynabook Inc
EMC Corporation
Google
Huawei Technologies Co., Ltd
IBM
ICC Intelligent Platforms GmbH
INSPUR (Beijing) Electronic Information Industry Co., Ltd.
Linaro Ltd.
Login Informatica Com. Repr. LTDA
Loongson Technology Corporation Limited
Marvell Asia Pte. Ltd.
Meta Platforms, Inc. (Facebook)
Montage Technology
Multilaser Industrial S/A
Nanjing Byosoft Co., Ltd.
NVIDIA
NXP B.V.
Oracle America, Inc.
Positivo Tecnologia S.A.
Qualcomm Inc.
Realtek Semiconductor Corp.
Red Hat, Inc.
Rivos Inc.
Seagate Technology LLC
SIFIVE, INC.
SUPER MICRO Computer, Inc.
SUSE LLC
Synaptics (DisplayLink (UK) Limited)
Tachyum Inc
The Linux Foundation
The MITRE Corporation
Ventana Micro Systems Inc.
VMware, Inc.
Western Digital Technologies
xFusion Digital Technologies Co., Ltd.
Xilinx, Inc.
Zoom Tecnologia Ltda.

ADOPTERS

3MD dba Hard Drives NW
3MDEB Embedded Systems Consulting
9elements GmbH
A.D. Nieman & Associates, LLC
AAEON Technology Inc.
ACAS Technologies, Inc.
Accusys, Inc.
Acer Inc.
Adaptec, Inc.
ads-tech GmbH
Advantech Co., Ltd.
AGN Group Suprimentos
AGS Sundyne Technologies Pvt. Ltd.
Airdesk Ltd.
Alcor Micro Corp.
Allion Labs, Inc.
ALTELL Ltd.
AlterSciences
American Arium
AMOI Electronics Co., Ltd.
Anna University - College of Engineering
Apricorn
Arca Noae, LLC
Arista Corp.
Arquimedes Automacao E Informatica LTDA.
ASSET InterTech, Inc.
AssurAware, Inc.
Ationa Inc.
ATTO Technology
AuthenTrend Technology Inc.
Authorizer Technologies, Inc.
Aver Networks Corp.
Avery Design Systems
Avery Design Systmes
Avid Technology, Inc.
Axiom Electronics, LLC
Axiomtek Co., Ltd.
Balance Software Corp.
Battelle Memorial Institute, Pacific Northwest Division
BCM Advanced Research
BedRock Systems, Inc.
Beijing AnHeng SecoTech Information Technology Co., Ltd.
BINARLY Inc.
BITMICRO Networks Inc.
Booz Allen Hamilton
Brown's Operating System Services Limited
BSQUARE Corporation
CalDigit, Inc.
Calxeda, Inc.
Canon Inc.
Captec Ltd.
Centerm Information Co., Ltd.
CenterTools Software GmbH
Central South University
Check Point Software
Chelsio Communications, Inc.
China Greatwall Computer Shenzhen Co., Ltd.
CHUNGHSIN INDUSTRY GROUP
CircleSoft LLC
Circuitco
Cisc Systems
Computer Task Group
Concurrent Technologies Plc
congatec A.G.
conpal GmbH
coresystems GmbH
Courtyard Electronics Ltd.
Cray, Inc.
CrossInfo Architects
Cryptomill Technologies Ltd.
CSWL, Inc.
Dawning Information Industry (Beijing) Corp., Ltd. (Sugon)
Def-Logix, Inc.
Denali Software
DeviceVM, Inc.
Diablo Technologies, Inc.
Dialogue Technology Corp.
Diskeeper Corporation
Dot Hill
Eclypsium, Inc
Egis Technology Inc.
Elite Group Computer Systems Co., Ltd.
EliteBytes Limited
Eltan B.V.
Embedded Now, Inc
Embedded Research Solutions
emBoot Inc.
Emerson Network Power, Embedded Computing
EMUTEX LTD.
Enmotus, Inc.
EPEAK Studio Ltd.
Etegro Technologies
Eurosoft (UK) Ltd.
EVOC
ExpressLuck Industrial Ltd.
Extreme Engineering Solutions, Inc.
F5 Networks, Inc.
Fastwel Group Co., Ltd.
Federal University of Ceara, Brazil
Fermilab
FernUniversität in Hagen
FirmTek, LLC
Flextronics Instituto de Tecnologia
focian Computer
Founder Technology Group Corp.
Framework Computer LLC
Freescale Semiconductor, Inc.
Fujitsu Ltd.
Gemalto SA
General Dynamics Canada
Genesi USA Inc.
Gigabyte United Inc.
GIT Japan Inc.
Glacier Peak Technology, LLC
Grain Media, Inc.
Greencroft Code
Guidance Software, Inc.
HighPoint Technologies, Inc.
Hitachi, Ltd.
Houter Brasil Eireli
HTC Corporation
Hunan New Cloudnet Technology Co., Ltd.
HXT Semitech
IATECAM
ICP Electronics, Inc.
InfoTeCS
Infrant Technologies, Inc.
Inphi Corp.
Institute of Physics, Academia Sinica
Integrated Device Technology Inc.
Intellico, LLC
Intelligency
Intelligraphics, Inc.
Inventec Corporation
Inventec Electronic (Tianjin) Co., Ltd.
IRCONA
ISP RAS
ITSC Library
Japan Digital Laboratory Co., Ltd.
JARI
Jetway Information Security Industry Co., Ltd.
KingTrust Systems Ltd.
Kioxia Corporation
Konsulko Group
Kontron Embedded Modules GmbH
Kraftway Corporation PLC
Kuhrman Technology Solutions LLC
LCC Rubinteh
LCFC
LG Electronics
Lockheed Martin Corporation
Lonxium Semiconductor Corporation
LucidLogix
Matrixed Reality Technology Co., Ltd.
Matrox Graphics Inc.
MBDA UK Ltd.
MBM Tecnologia e Industria de Informatica LTDA
MediaTek Inc.
MediCapture, Inc.
Mensys B.V.
Mercury Computer Systems
Micro-Star Int'l Co., Ltd
Microchip Technology
Micron Technology, Inc.
Microsemi Corporation
Mitrastar Technology Corp.
MokaFive
Mossbit Technologies
Myricom, Inc.
National Instruments Corporation
National Technical Systems
Naval Postgraduate School
NEC Personal Products Ltd.
Neterion, Inc.
Netlist Inc.
Network 2000 Inc.
NetXen Inc.
Neusoft
New H3C Technologies Co., Ltd.
Newport Enterprises Inc.
Nextiva
NOLO Co., Ltd.
NTI Corporation
NVELO, Inc.
OpenMars Development LLC
Order N Development, LLC
Orion Technologies, LLC
OSBASE, LLC
Panasonic Corporation
Parallels IP Holdings GmbH
Pegatron Corporation
Peppercon AG
PGP Corporation
PixelNext Inc.
PLX Technology, Inc.
Portlock
PQURE Technology AB
Proformatique
Quanta Computer Inc.
Radisys Corporation
Red Flag Software Co., Ltd.
Renesas Electronics Corporation
RPA RusBITech
rubbersoft.com
Ruijie Networks
Sage-Microelectronics
Samsung Electronics Co., Ltd.
Sandia National Laboratories
SanDisk Corporation
Sanmina Corporation d/b/a Viking Technology
SDL Eletro Eletronica Ltda - EPP
SecurStar GmbH
SEMP TOSHIBA INFORMATICA LTDA
Sensics, Inc.
ServerEngines Corp.
Shanghai Advanced Research Institute
Shanghai IP3 Technology Co., Ltd.
Silicon Image, Inc.
Silicon Integrated Systems Corp.
SinoSun Technology, Ltd.
SoftIron, Inc.
softKVM LLC
Solarflare Communications Inc.
Sony Corporation
Spirent Communications
Sprezzatech
SSWW
STEC, Inc.
Stonewood Electronics Ltd.
Stream Labs
Super Future Equities, Inc.
SYBERA GmbH
Symantec Corporation
System Fabric Works
System Garden Ltd.
TCORP
Terascala, Inc.
Themis Computer, Inc.
TimeLab Corporation
Tokyo Electron Device Ltd.
Toshiba Samsung Storage Technology Korea Corporation
Trend Micro
Tsinghua Tongfang Co., Ltd.
Tuxera Inc.
TYA
Ubiquitous AI Corporation
ULINK Technology, Inc.
UNH InterOperability Laboratory
Unicompute Technology Co., Ltd
UniFabriX Ltd.
Unisys Corporation
University of California, Davis
UPEK, Inc.
US Technology Resources (M) SDN. BHD.
V&G Information System Co., Ltd.
VAIO Corporation
Validity Sensors
Venetex Corp
Vestel Dijital Yretim Sanayi A. S.
VIA Alliance Semiconductor Co., Ltd.
VIA Technologies, Inc.
VNPT Technology
VT Miltope
Wacom Technology
Wave Systems Corp.
WinMagic Inc.
Winsiders Seminars & Solutions, Inc.
WinSystems, Inc.
Winwynn Corporation
Wuhan University
Wyse Technology
XGI Technology Inc.
Xi'an Saming Technology Co., Ltd.
Xi3 Corporation
Xitrix Computer Corporation
Xsense Connectivity Inc.
Zhejiang Dahua Technology Co., Ltd.
ZNYX Networks

INDIVIDUAL ADOPTERS

Alex Kunovszky
Barry Gian James
Benson Lin
Cheng-Lung Chang
Connor Horman
Connor Wood
David Boyd
Dharmesh Tarapore
Don MacKellar
Ed Brundage
Elika S. Kohen
Gail B. Keown
George Fulk
Gregory Havenga
Howard Peng
Ing-chao Lin
Jake Lehotsky
James Bottomley
Jason Christopher Stone
Jeong Kim
John A. Newton
John Blacker
John M. Hare
Jonathan J. Willemin
Joseph LeGarreta
Juan Pablo Black Romero
Justin Loo
Justin Sligh
Karl O. Van Leuven IV
Kushal Koolwal
Lee Fisher
Liqiang Ni
Lucien Pullen
Marvin Häuser
Michael Johnston
Michael Zimmermann
Patrick J. Kennedy
Paulo Henrique L. Amorim
Pete Batard
Phooen Sonpooshi
Piryanshu Pareek
Priyanshu Pareek
Robert Jandacek
Robert Johnston
Rocky Wang
Roger Bertoldi
Roger Thompson
Seppe Sol
Shannon Lewis
Shawn M. Pedersen
VALETTE Teddy
Wang Qiang
William J. Biessman
Xie Tianming (Persmule)
ZongQi Li

* temporarily suspended

OVERVIEW

1. USB-A (USB 5Gbps)	5. USB-C (USB 10Gbps), with USB PD 3.0 & DP 1.4
2. Ethernet (RJ-45)	6. USB-A (USB 10Gbps), Always On
3. Kensington Nano Security Slot	7. HDMI
4. USB-C (USB 5Gbps), with USB PD 3.0 & DP 1.4	8. Headphone / microphone combo jack (3.5mm)

PERFORMANCE

Processor

Processor Family

AMD Ryzen™ 3 / 5 / 7 Processor

Processor**

Processor Name	Cores	Threads	Base Frequency	Max Frequency	Cache	Processor Graphics
AMD Ryzen™ 3 7335U	4	8	3.0GHz	4.3GHz	2MB L2 / 8MB L3	AMD Radeon™ 660M
AMD Ryzen™ 5 7535HS	6	12	3.3GHz	4.55GHz	3MB L2 / 16MB L3	AMD Radeon™ 660M
AMD Ryzen™ 5 7535U	6	12	2.9GHz	4.55GHz	3MB L2 / 16MB L3	AMD Radeon™ 660M
AMD Ryzen™ 7 7735HS	8	16	3.2GHz	4.75GHz	4MB L2 / 16MB L3	AMD Radeon™ 680M
AMD Ryzen™ 7 7735U	8	16	2.7GHz	4.75GHz	4MB L2 / 16MB L3	AMD Radeon™ 680M

Operating System

Operating System**

- Windows® 11 Pro
- Windows® 11 Home
- Windows® 11 Home Single Language
- No preload operating system

Graphics

Graphics**

Graphics	Type	Memory	TGP	Key Features
AMD Radeon™ 660M	Integrated	Shared	Share CPU TDP	DirectX® 12
AMD Radeon™ 680M	Integrated	Shared	Share CPU TDP	DirectX® 12

Monitor Support

Monitor Support

Supports up to 4 independent displays (native display and 3 external monitors via HDMI® and USB-C®)
• HDMI® supports up to 4K@60Hz
• USB-C® (USB 10Gbps) supports up to 5K@60Hz
• USB-C® (USB 5Gbps) supports up to 4K@60Hz

Chipset

Chipset

AMD SoC (System on Chip) platform

Memory

Max Memory[1]

Up to 64GB DDR5-4800

Memory Slots

Two DDR5 SO-DIMM slots, dual-channel capable

Memory Type

DDR5-4800

Notes:

[1] Maximum memory is only to test technical readiness of notebook but not shipped by Lenovo®.

Storage

Storage Support[1]

Up to two drives, 2x M.2 SSD
• M.2 2242 SSD up to 1TB
• M.2 2280 SSD up to 1TB

Storage Slot

Two M.2 slots
• One M.2 2242 PCIe® 4.0 x4 slot
• One M.2 2280 PCIe® 4.0 x4 slot

Storage Type***

Disk Type	Interface	Offering	Security
M.2 2242 SSD	PCIe® NVMe®, PCIe® 4.0 x4	256GB / 512GB / 1TB	Opal 2.0
M.2 2280 SSD	PCIe® NVMe®, PCIe® 4.0 x4	1TB	Opal 2.0

Notes:

[1] The system supports dual SSD via two M.2 slots, but Lenovo® only offers one M.2 2242 SSD configuration and M.2 2280 slot for user self-extension.

Removable Storage

Card Reader

No card reader

Multi-Media

Audio Chip

High Definition (HD) Audio, Senary SN6141 codec

Speakers

Stereo speakers, 2W x2, Dolby Atmos®, audio by HARMAN

Microphone

Dual-microphone array with smart noise-cancelling

Camera**

- FHD 1080p + IR hybrid, with privacy shutter, fixed focus, temporal noise reduction
- FHD 1080p, with privacy shutter, fixed focus, temporal noise reduction
- HD 720p, with privacy shutter, fixed focus

Battery

Battery**[1]

- Integrated Li-Polymer 47Wh battery, supports Rapid Charge Pro (charge up to 50% in 30min)
- Integrated Li-Polymer 57Wh battery, supports Rapid Charge (charge up to 80% in 1hr)

Battery Life[2]

Configuration 1 (max battery life)
MobileMark® 25: up to 13.5 hr with 588 performance score @250nits
JEITA 3.0 (Video/Idle): up to 11.76 hr / 21.8 hr @200nits
Local video playback: up to 19.59 hr @150nits

Alternate configuration 2
MobileMark® 25: up to 13.08 hr with 604 performance score @250nits
JEITA 3.0 (Video/Idle): up to 11.75 hr / 20.1 hr @200nits
Local video playback: up to 18.84 hr @150nits

Alternate configuration 3
MobileMark® 25: up to 10.1 hr with 667 performance score @250nits
JEITA 3.0 (Video/Idle): up to 8.4 hr / 16.3 hr @200nits
Local video playback: up to 14.65 hr @150nits

Notes:

[1] Rapid charge is only guaranteed when the computer is turned off or in standby mode or in hibernation mode. When the computer is powered on, the Charge Time will vary depending on system power consumption and AC adapter power.
[2] Configuration 1 (max battery life): WUXGA (non-touch), AMD Ryzen™ 7 7735HS, 8GB DDR5, Win 11, 57Wh battery, best power efficiency power mode
Alternate configuration 2: WUXGA (non-touch), AMD Ryzen™ 7735U, 8GB DDR5, Win 11, 57Wh battery, best power efficiency power mode
Alternate configuration 3: WUXGA (touch), AMD Ryzen™ 5 7535U, 8GB+8GB DDR5, Win 11, 47Wh battery, best power

efficiency power mode

All battery life claims are approximate maximum and based on results using MobileMark® 25, JEITA 3.0, continuous 1080p local video playback (using default Media Player in Fullscreen mode with 150nits brightness and default volume level), or Google Power Load Test (PLT) battery-life benchmark tests.
Actual battery life will vary depending on many factors such as product configuration, software, wireless functionality, power management settings, and screen brightness.
The maximum capacity of the battery will decrease with time, ambient temperature and use.
Refer to Microsoft® link for more information about the Windows® Performance power slider.

Power Adapter

Power Adapter[**][1]

- 65W USB-C® (2-pin) AC adapter, supports PD 3.0, 100-240V, 50-60Hz
- 65W USB-C® (3-pin) AC adapter, supports PD 3.0, 100-240V, 50-60Hz
- No power adapter[2]

Notes:

[1] AC adapter offerings depend on the country.
[2] No power adapter is for special bid only.

DESIGN

Display

Display[**]

Size	Resolution	Touch	Type	Brightness	Surface	Aspect Ratio	Contrast Ratio	Color Gamut	Refresh Rate	Viewing Angle (L/R/U/D)	Key Features
14″	WUXGA (1920x1200)	None	IPS[1]	300nits	Anti-glare	16:10	800:1	45% NTSC	60Hz	85° / 85° / 85° / 85°	TÜV Low Blue Light (Software)
14″	WUXGA (1920x1200)	Multi-touch	IPS[2]	300nits	Anti-glare	16:10	800:1	45% NTSC	60Hz	85° / 85° / 85° / 85°	TÜV Low Blue Light (Software)
14″	2.2K (2240x1400)	None	IPS[3]	300nits	Anti-glare	16:10	1500:1	100% sRGB	60Hz	85° / 85° / 85° / 85°	Eyesafe® Certified 2.0

Touchscreen

- On-cell multi-touch, supports 10-point touch
- Non-touch

Notes:

[1], [2], [3] IPS (in-plane switching) technology may refer to IPS, PLS, ADS, AHVA, AAS.

Input Device

Pen

No support

Keyboard

6-row, spill-resistant, multimedia Fn keys, Copilot key

Keyboard Backlight

- LED backlight
- Non-backlight

UltraNav™

TrackPoint® pointing device, double-tap to open the TrackPoint® Quick Menu
Mylar® surface multi-touch touchpad, 56 x 115 mm (2.24 x 4.53 inches)

Mechanical

Dimensions (WxDxH)[1]

Models	Dimensions
Models with aluminium (top) and aluminium (bottom)	313 x 219.3 x 17.99 mm (12.32 x 8.63 x 0.71 inches)
Models with aluminium (top) and PC-ABS (bottom)	313 x 219.3 x 18.59 mm (12.32 x 8.63 x 0.73 inches)

Weight[2]

Models	Weight
Models with aluminium (top) and aluminium (bottom)	Starting at 1.44 kg (3.17 lbs)
Models with aluminium (top) and PC-ABS (bottom)	Starting at 1.42 kg (3.14 lbs)

Case Color**

- Black
- Grey

Case Material**

- Aluminium (top), PC-ABS (bottom)
- Aluminium (top), aluminium (bottom)

Notes:

[1] The system dimensions may vary depending on configurations.
[2] The system weight is approximate and based on results in Lenovo® lab, which varies depending on the source of component, variance of the distribution of each component, and manufacturing process. It may not be the exact weight for each specific model.

CONNECTIVITY

Network

Ethernet

Gigabit Ethernet, Realtek® RTL8111H-CG, 1x RJ-45, supports Wake-on-LAN

WLAN + Bluetooth®**[1]

- Wi-Fi® 6, 802.11ax 2x2 Wi-Fi® + Bluetooth® 5.3, M.2 card
- MediaTek Wi-Fi® 6 MT7921, 802.11ax 2x2 Wi-Fi® + Bluetooth® 5.3, M.2 Card
- Realtek® Wi-Fi® 6 RTL8852BE, 802.11ax Dual Band 2x2 Wi-Fi® + Bluetooth® 5.3, M.2 card
- Wi-Fi® 6E, 802.11ax 2x2 Wi-Fi® + Bluetooth® 5.3, M.2 card[2]
- Realtek® Wi-Fi® 6E RTL8852CE, 802.11ax Dual Band 2x2 Wi-Fi® + Bluetooth® 5.3, M.2 card[3]

WWAN

No support

SIM Card

No physical SIM card inbox

NFC

No support

Notes:

[1] Bluetooth® may operate at a lower version than hardware design depending on the factors such as operating system, driver, etc.
[2], [3] Wi-Fi® 6E full features might be limited by country-level restrictions.
6GHz Wi-Fi® 6E operation is dependent on the support of the operating system, routers/APs/Gateways that support Wi-Fi® 6E, and the regional regulatory certifications & spectrum allocation.
Bluetooth® 5.3 operation requires Windows® 11. For more information please visit General Bluetooth® Support Information on Microsoft®.

Ports[1]

Standard Ports

- 1x USB-A (USB 5Gbps / USB 3.2 Gen 1)
- 1x USB-A (USB 10Gbps / USB 3.2 Gen 2), Always On
- 1x USB-C® (USB 5Gbps / USB 3.2 Gen 1), with USB PD 3.0 and DisplayPort™ 1.4
- 1x USB-C® (USB 10Gbps / USB 3.2 Gen 2), with USB PD 3.0 and DisplayPort™ 1.4
- 1x HDMI® 2.1, up to 4K/60Hz

- 1x Headphone / microphone combo jack (3.5mm)
- 1x Ethernet (RJ-45)

Notes:

[1] The transfer speed of the ports will vary and, depending on many factors, such as the processing speed of the host device, file attributes and other factors related to system configuration and your operating environment, will be slower than theoretical speed.

Docking

Docking

Various docking solutions supported via USB-C®.
For more compatible docking solutions, please visit Docking for ThinkPad® E14 Gen 6 (AMD)

SECURITY & PRIVACY

Security

Security Chip**

- Discrete TPM 2.0, TCG certified, FIPS 140-2 certified
- Discrete TPM 2.0 (TCG certified, FIPS 140-2 certified) and Microsoft® Pluton TPM 2.0, one enabled at one time

Physical Locks

Kensington® Nano Security Slot™, 2.5 x 6 mm

Smart Card Reader

No smart card reader

Fingerprint Reader

- Touch style fingerprint reader integrated in power button, match-on-chip
- No fingerprint reader

BIOS Security

- NVMe® password
- Power-on password
- Supervisor password
- System management password
- Certificate based BIOS authentication
- FIDO (Fast Identity Online) authentication
- Self-healing BIOS
- More BIOS security features, please visit BIOS Simulator

Other Security

- Camera privacy shutter
- (Optional) IR camera for Windows® Hello (facial recognition)

MANAGEABILITY

System Management

System Management

Non-DASH

SERVICE

Warranty

Base Warranty**

- 1-year mail-in service
- 1-year courier or carry-in service
- 1-year courier or carry-in with 2-year system board service (Korea only)
- 1-year limited onsite service
- No base warranty

ACCESSORIES

Bundled Accessories

Bundled Accessories[1]

None

Notes:

[1] For more compatible accessory solutions, please visit Accessories for ThinkPad® E14 Gen 6 (AMD).

OPERATING REQUIREMENTS

Operating Environment

Temperature[1]

- Operating: 5°C (41°F) to 35°C (95°F)
- Storage and transportation in original shipping package: -20°C (-4°F) to 60°C (140°F)
- Storage without package: 5°C (41°F) to 43°C (109°F)

Relative Humidity

- Operating: 8% to 95% at wet-bulb temperature 23°C (73°F)
- Storage and transportation: 5% to 95% at wet-bulb temperature 27°C (81°F)

Altitude

Maximum altitude (without pressurization): 3048 m (10,000 ft)

Notes:

[1] When you charge the battery, its temperature must be no lower than 10°C (50°F).

ENVIRONMENTAL

Sustainability

Material[1]

25% PCC recycled plastic used in the battery pack enclosure
30% PCC recycled plastic used in speaker enclosure
90% PCC recycled plastic used in standard 65W adapter
Plastic free packaging
Dry-pressed bamboo & sugarcane fiber Cushions
FSC Certified paper in packaging

Notes:

[1] PCC: Post Consumer Content, recycled materials from customers.

CERTIFICATIONS

Green Certifications[1]

Green Certifications[2]

- ENERGY STAR® 8.0
- EPEAT™ Gold Registered[3]
- ErP Lot 6/26
- RoHS compliant
- TCO Certified 9.0

Notes:

[1] The items listed under the "Green Certifications" section may not only refer to certification but also registration or self-declaration. For ESG & regulatory compliance documents, please visit https://compliance.lenovo.com.

[2] EPEAT™ registration and ENERGY STAR® certification are optional and only available on the models with preloaded OS. Please visit epeat.net and energystar.gov for more information.

[3] EPEAT™ is registered where applicable, please visit epeat.net for registration status by country.

Other Certifications

Mil-Spec Test

MIL-STD-810H military test passed

Other Certifications

- (Optional) Eyesafe® Certified 2.0
- (Optional) TÜV Rheinland® Low Blue Light (Hardware Solution)
- (Optional) TÜV Rheinland® Low Blue Light (Software Solution)

- Feature with ** means that only one option listed under the feature can be configured on selected models. Please refer to the model configuration for specific information.
- Feature with *** means that one or more options listed under the feature can be configured on selected models. Please refer to the model configuration for specific information.
- Lenovo reserves the right to change specifications or other product information without notice. Lenovo is not responsible for photographic or typographical errors. LENOVO PROVIDES THIS PUBLICATION “AS IS,” WITHOUT WARRANTY OF ANY KIND, EITHER EXPRESS OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. Some jurisdictions do not allow disclaimer of express or implied warranties in certain transactions, therefore this disclaimer may not apply to you.
- The specifications on this page may not be available in all regions, and may be changed or updated without notice.


WOOD
WORK

Members List

Board

Broadcom Inc.
Cisco
Dell Technologies
Hewlett Packard Enterprise
Intel Corporation
Lenovo
NetApp
Positivo Tecnologia S.A.
Verizon

Leadership

Advanced Micro Devices
Alibaba (China) Co., Ltd
Daten Tecnologia Ltda
Ericsson AB
Google LLC
HP, Inc
Huawei
IBM
Inspur
NVIDIA Corporation
Seagate Technology
Supermicro
Vertiv
VMware Inc.
xFusion Digital Technologies Co., Ltd.

Participation

AdaCore SAS
American Megatrends, Inc.
Ampere Computing LLC
ARM, Inc
Atos
Cornelis Networks, Inc.
Eaton
Fujitsu
Futurewei
Groq
Jabil
KIOXIA Corporation
LOGIN INFORMATICA
Loongson Technology Corporation Limited
Marvell Asia Pte, Ltd.
Meta
Microchip Technology Inc.
Micron Technology, Inc.
MULTILASER INDUSTRIAL S/A
Phoenix Technologies Ltd.
Qualcomm Inc
Quanta Computer Inc
Realtek Semiconductor
Solidigm
Synopsys
US Department of Defense
VIA Technologies, Inc.
Western Digital Technologies, Inc.
Xilinx Inc
ZT Systems

Alliance Partner

Learn more: Current Work Registers

ASHRAE
Broadband Forum (BBF)
China Communications Standards Association
China Electronics Standardization Institute (CESI)
CXL Consortium
ETSI-NFV
Gen-Z
HDBaseT
MIPI Alliance
NVM Express
OMG-Cloud Working Group
Open Compute Project (OCP)
Open Data Center Committee (ODCC)
Open Fabrics Alliance (OFA)
Open Grid Forum
OpenStack Foundation
PCI Industrial Computer Manufacturer Group (PICMG)
PCI-SIG
Storage Networking Industry Association
TeleManagement Forum
The Green Grid
The Open Group
Unified Extensible Firmware Interface

Academic Alliance

"Gheorghe Asachi" Technical University of Iaşi
Athens University of Economics and Business
Dongguk University
Federal Institute of Technology of Espirito Santo
George Mason University
Hungarian Academy Of Sciences Institute For Computer Science And Control
Indian Institute of Technology Roorkee
Institute of Information Security (IISEC)
Kasetsart University
Logitrain
Marshall University
National Technical University of Athens
Paul Sabatier University
Research Center on Scientific and Technical Information (CERIST)
Ruprecht-Karls-University Heidelberg
Shanghai Jiao Tong University
Swami Rama Himalayan University
Technische Universitaet Dresden
Texas Tech University
Universidade de Sao Paulo
University of California
University of New Hampshire
University of Pisa - Italy
University of Seville
University of Sydney
University of Western Ontario
University of Wuerzburg

CIM Forum Leadership

Advanced Micro Devices
Broadcom Inc.
Dell Technologies

CIM Forum Participatory

HP, Inc
Lenovo
Realtek Semiconductor
Western Digital Technologies, Inc.

Redfish Forum Promoter

Cisco
Dell Technologies
Ericsson AB
Hewlett Packard Enterprise
IBM
Inspur
Intel Corporation
Lenovo
Supermicro
Verizon
Vertiv
VMware Inc.

Redfish Forum Supporter

Advanced Micro Devices
Alibaba (China) Co., Ltd
American Megatrends, Inc.
ARM, Inc
Eaton
Fujitsu
Google LLC
Huawei
Jabil
KIOXIA Corporation
Meta
Microchip Technology Inc.
NetApp
NVIDIA Corporation
Phoenix Technologies Ltd.
Quanta Computer Inc
Seagate Technology
Xilinx Inc

About DMTF

All About DMTF
Frequently Asked Questions
Members List
DMTF Officers
All DMTF Officers
DMTF Executive Biographies
DMTF Officer Hall of Fame
DMTF Fellows
DMTF Star Award Recipients
All Star Award Recipients
Super Star Award Recipients
Working Groups and Committees
Alliance Partners
Academic Alliances
ANSI/ISO Adoptions and Alliance Activities
Policies
Patent Disclosures
Copyright Statement
Contact Us

DMTF Board Member Companies

Hewlett Packard Enterprise

See all DMTF Member Companies »

Microsoft

Hardware certification report **Approved**

Private product ID:	**14194778660326778**
Shared product ID:	**401690536**
Submission ID:	**1152921505697481764**
Submission date:	**3/12/2024**
Completion date:	**3/12/2024**
Company:	**Lenovo**
Product name:	**ThinkPad E14 Gen 6 AMD Win11**
Category:	**System**
Product type:	**Laptop with Touch**
Qualification level:	**Certified for Microsoft Windows 11 Client family version 22H2, x64**
Marketing name:	**ThinkPad E14 Gen 6 21M3** **ThinkPad E14 Gen 6 21M4**

CERTIFICATE

Certificate Number: 111969.00
With Two Page Addendum

The Quality Management System and implementation of:

Lenovo Group, LTD

With Central Functions At:
8001 Development Drive
Morrisville, NC 27560
United States

meets the requirements of the standard:

ISO 9001:2015

Scope:

Design, development, manufacturing, distribution, fulfillment, and repair of computer products and devices, data center products, mobile devices, smart devices, and accessories.

Certification Structure: Multi-site

Certificate Expires:	June 30, 2025
Certificate Issued:	July 01, 2022
Certified Since:	July 01, 2016

Dr. Cem O. Onus
Managing Director
DEKRA Certification, Inc.
1120 Welsh Road, Suite 210
North Wales, PA 19454 USA
(215) 997-4519
http://www.dekra.us/en/audit

ANAB
ANSI National Accreditation Board
ACCREDITED
ISO/IEC 17021-1
MANAGEMENT SYSTEMS CERTIFICATION BODY

MEMBER OF MULTILATERAL RECOGNITION ARRANGEMENT
IAF

CERTIFICATE ADDENDUM

Certificate Number: 111969.00
ADDENDUM Page One of Two

The Quality Management System and implementation of:

Lenovo Group, LTD

meets the requirements of the standard:

ISO 9001:2015

Site Address	Scope Per Site:
Central Function: 8001 Development Drive; Morrisville, NC 27560 USA	Responsibility of the company's overall QMS through the management of documentation/changes, management review, corrective actions, internal audit, planning/evaluation and compliance to applicable requirements.
8001 Development Drive; Morrisville, NC 27560 USA	Design, development, fulfillment, services, marketing, and sales of computer products and devices, data center products, mobile devices, smart devices, and accessories.
19/1A, & 2A Edayar, Cuddalore Main Road, Edayar Palayam Village – Pondicherry, India	Manufacturing of computer products and devices.
Plant #1: Boulevard Escobedo No 316, Apodaca Technology Park, Apodaca, Nuevo Leon C.P. 66600 Plant #2: Boulevard Escobedo No 318, Apodaca Technology Park, Apodaca, Nuevo Leon C.P. 66627	Manufacturing of computer products and devices, and data center products.
Estrada Municipal José Costa de Mesquita, 200 – Chácara Alvorada – Indaiatuba/SP, Brazil	Manufacturing of computer products and devices, and data center products.

Certificate Expires: June 30, 2025
Certificate Issued: July 01, 2022
Certified Since: July 01, 2016

Dr. Cem O. Onus
Managing Director
DEKRA Certification, Inc.
1120 Welsh Road, Suite 210
North Wales, PA 19454 USA
(215) 997-4519
http://www.dekra.us/en/audit

ANAB ANSI National Accreditation Board ACCREDITED ISO/IEC 17021-1 MANAGEMENT SYSTEMS CERTIFICATION BODY

MEMBER OF MULTILATERAL RECOGNITION ARRANGEMENT IAF

CERTIFICATE ADDENDUM

Certificate Number: 111969.00
ADDENDUM Page Two of Two

The Quality Management System and implementation of:

Lenovo Group, LTD

meets the requirements of the standard:

ISO 9001:2015

Site Address	Scope Per Site:
6540 Franz Warner Parkway; Whitsett, NC 27377 USA	Manufacturing, distribution, fulfillment and services of computer products and devices, data center products, mobile devices, smart devices, and accessories.
Digital Park, Einsteinova 851 01; Bratislava, Slovakia	Fulfillment, services, marketing, and sales of computer products and devices, data center products, mobile devices, smart devices, and accessories.
Minatomiral Center Building; 2F 3-6-1; Minatomiral, Nishi-Ku; Yokohama, Japan	Design and development of computer products and devices.
Motorola Mobility LLC: 222 W Merchandise Mart Plaza, Chicago, IL 60654 USA	Design, development, fulfillment, services, marketing, and sales of computer products and devices, data center products, mobile devices, smart devices, and accessories.
K-Sped krt. 28, Ullo, 2225 Hungary	Manufacturing of computer products and devices, and data center products.
C/Puerto de Somport 9 Planta 1 (Ed. Oxxeo) - 28050 Madrid Spain	Fulfillment, services, marketing, and sales of computer products and devices, data center products, mobile devices, smart devices, and accessories.
Sants FirstWorkplace Carrer de Tarragona 161, planta 13. 08014 Barcelona, Spain	Fulfillment, services, marketing, and sales of computer products and devices, data center products, mobile devices, smart devices, and accessories.

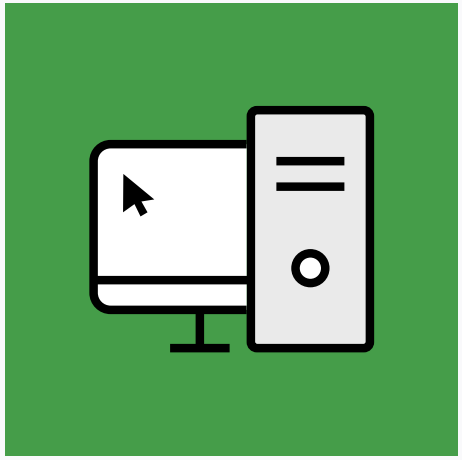
Certificate Expires: June 30, 2025
Certificate Issued: July 01, 2022
Certified Since: July 01, 2016

Dr. Cem O. Onus
Managing Director
DEKRA Certification, Inc.
1120 Welsh Road, Suite 210
North Wales, PA 19454 USA
(215) 997-4519
http://www.dekra.us/en/audit

ANAB
ANSI National Accreditation Board
ACCREDITED
ISO/IEC 17021-1
MANAGEMENT SYSTEMS CERTIFICATION BODY

MEMBER OF MULTILATERAL RECOGNITION ARRANGEMENT
IAF

RETURN TO SEARCH



COMPUTERS & DISPLAYS

ThinkPad E14 Gen 6 (AMD)

Product Summary:

Product Type:	**Notebook**
Registered In:	**United States**
Manufacturer:	**Lenovo**
EPEAT Tier:	**Gold**
Registration Date:	**2024-04-01**
Product Status:	**Active**
Manufacturer Part Number(s):	**21M3, 21M4**

All unique product identifiers existing for this product may not be listed here. If the unique product identifier you are looking for is not listed, please contact EPEAT at EPEAT@GEC.org.

EXPORT PRODUCT SUMMARY

EPEAT Tier Score Detail

For a product to be listed on the EPEAT Registry, it must, at a minimum, meet the applicable "required" criteria. Click here to see a list of the required criteria for this product category.

This product has met the necessary required criteria.

Along with required criteria, products can also meet optional criteria and score optional points. It is not required for a product to achieve any optional points.

Products that meet all required criteria and achieve **less than 50%** of the optional points are rated at
EPEAT Bronze

Products that meet all required criteria and achieve **50 - 74%** of the optional points are rated at
EPEAT Silver

Products that meet all required criteria and achieve **75 - 100%** of the optional points are rated at
EPEAT Gold

The optional criteria for this product category and optional points achieved by this product are listed below.

Optional Criteria	Scores
+ 4.1 Substance Management	13 / 16
+ 4.2 Materials Selection	1 / 3
+ 4.4 Product longevity/life-cycle extension	4 / 4

4.5 Energy Conservation	3 / 3
4.7 Packaging	2 / 2
4.8 Life cycle assessment and carbon footprint	6 / 6
4.9 Corporate Environmental Performance	9 / 9
4.10 Corporate social responsibility	2 / 6
TOTAL OPTIONAL CRITERIA SCORE:	**40 / 49**

Please note that it is not required for a product to achieve any optional points.

Some optional criteria may not be applicable to a product. Optional criteria that are not applicable (N/A) to the product are not included in the Total Optional Criteria Score, and are not reflected above.

For any questions, comments, or feedback regarding the EPEAT Registry, please contact us.

Contact Us

+1.503.279.9383

PO Box 12149 Portland, OR 97212-0149 USA

Stay connected with regular updates from EPEAT

Sign up

EPEAT Registry Privacy Policy

EPEAT Registry Terms of Use

CERTIFICATE

Certificate Number: 141968.00
With One Page Addendum

The Environmental Management System and implementation of:

Lenovo Group, LTD

With Central Functions At:
8001 Development Drive
Morrisville, NC 27560
United States

meets the requirements of the standard:

ISO 14001:2015

Scope:

Design, development, manufacturing, distribution, fulfillment, and repair of computer products and devices, data center products, mobile devices, smart devices, and accessories.

Certification Structure: Multi-site

Certificate Expires:	July 16, 2025
Certificate Issued:	July 17, 2022
Certified Since:	July 17, 2013

Dr. Cem O. Onus
Managing Director

DEKRA Certification, Inc.
1120 Welsh Road, Suite 210
North Wales, PA 19454 USA
(215) 997-4519
http://www.dekra.us/en/audit

ANAB
ANSI National Accreditation Board
ACCREDITED
ISO/IEC 17021-1
MANAGEMENT SYSTEMS CERTIFICATION BODY

MEMBER OF MULTILATERAL RECOGNITION ARRANGEMENT
IAF

CERTIFICATE ADDENDUM

Certificate Number: 141968.00
ADDENDUM Page One of One

The Environmental Management System and implementation of:

Lenovo Group, LTD

meets the requirements of the standard:

ISO 14001:2015

Site Address	Scope Per Site:
Central Function: 8001 Development Drive; Morrisville, NC 27560 USA	Responsibility of the company's overall EMS through the management of documentation/changes, management review, corrective actions, internal audit, planning/evaluation and compliance to applicable requirements.
8001 Development Drive; Morrisville, NC 27560 USA	Design and development of data center products
19/1A, & 2A Edayar, Cuddalore Main Road, Edayar Palayam Village – Pondicherry, India	Manufacturing of computer products and devices.
Plant #1: Boulevard Escobedo No 316, Apodaca Technology Park, Apodaca, Nuevo Leon C.P. 66600 Plant #2: Boulevard Escobedo No 318, Apodaca Technology Park, Apodaca, Nuevo Leon C.P. 66627	Manufacturing of computer products and devices and data center products.
Estrada Municipal José Costa de Mesquita, 200 – Chácara Alvorada – Indaiatuba/SP, Brazil	Manufacturing of computer products and devices and data center products.
6540 Franz Warner Parkway; Whitsett, NC 27377 USA	Manufacturing, distribution, fulfillment, and repair of computer products and devices, data center products, mobile devices, smart devices, and accessories.
Am Zehnthof 77, 45307 Essen, Germany	Design and development of computer products and devices.
Minatomiral Center Building; 2F 3-6-1; Minatomiral, Nishi-Ku; Yokohama, Japan	Design and development of computer products and devices.
Motorola Mobility LLC: 222 W Merchandise Mart Plaza, Chicago, IL 60654 USA	Design and development of computer products and devices, data center products, mobile devices, smart devices, and accessories.
K-Sped krt. 28, Ullo, 2225 Hungary	Manufacturing of computer products and devices and data center products.

Certificate Expires: July 16, 2025
Certificate Issued: July 17, 2022
Certified Since: July 17, 2013

Dr. Cem O. Onus
Managing Director

DEKRA Certification, Inc.
1120 Welsh Road, Suite 210
North Wales, PA 19454 USA
(215) 997-4519
http://www.dekra.us/en/audit

ANAB
ANSI National Accreditation Board
ACCREDITED
ISO/IEC 17021-1
MANAGEMENT SYSTEMS CERTIFICATION BODY

MEMBER OF MULTILATERAL RECOGNITION ARRANGEMENT
IAF

ENERGY STAR CERTIFIED
Computers

Lenovo - ThinkPad E14 Gen 6 : 21M3

Specifications

ENERGY STAR Unique ID:	3417643
Brand Name:	Lenovo
Model Name:	ThinkPad E14 Gen 6
Model Number:	21M3
Type:	Notebook
Category 2: Processor Brand:	AMD
Category 2: Processor Name:	Ryzen 7
Category 2: Base Processor Speed Per Core (GHz):	3.2
Category 2: Physical CPU Cores (count):	8
Category 2: System Memory (GB):	64.0
Category 2: Default Low-power Mode:	Alternative Low Power Mode (ALPM)
Category 2: Long Idle Power Used for Sleep Mode:	Yes
Category 2: Off Mode (watts):	0.4
Category 2: Sleep Mode (watts):	0.8
Category 2: Long Idle (watts):	0.8
Category 2: Short Idle (watts):	4.6
Category 2: Base TEC Allowance (kWh):	14
Category 2: Functional Adder Allowances (kWh):	33.4
Category 2: TEC of Model (kWh):	14.3
Notebooks, Desktops, Integrated Computers, Slate/Tablets, Two-in-one Notebooks, and Portable All-in-ones Category for TEC (Typical Energy Consumption) Criteria:	2
Category 2: Operating System Name:	Windows 11 Pro
Sleep Mode Default Time Upon Shipment (min.):	5
Display Sleep Mode Default Time Upon Shipment (min.):	5
WOL (Wake on LAN) From Sleep:	Shipped Disabled
Will the Speed of Any Active 1 GB/s or Higher Ethernet Network Links be Reduced to Less Than 1 GB/s When Transitioning to Sleep or Off Mode?:	Yes
Ethernet Capability:	Yes

Touch Screen:	Yes
Date Available On Market:	1710820800000
Date Certified:	1709182800000
Markets:	United States, Switzerland, Taiwan, Japan, Canada
ENERGY STAR Certified:	Yes

Additional Model Information

ThinkPad E14 Gen 6,21M4,All models are identical except for model number for marketing purpose.

Captured On:
05/27/2024

Certificate CN19/31787.06

Lenovo Tecnologia (Brazil) Ltd.

Business Registration Address: ESTRADA MUNICIPAL JOSÉ COSTA DE MESQUITA, 200-BAIRRO CHÁCARA ALVORADA-MODULES 5 TO 10-INDAIATUBA / SP BRAZIL – ZIP CODE: 13.337-200 Brasil
Business Operation Address: ESTRADA MUNICIPAL JOSÉ COSTA DE MESQUITA, 200-BAIRRO CHÁCARA ALVORADA-MODULES 5 TO 10-INDAIATUBA / SP BRAZIL – ZIP CODE: 13.337-200 Brasil

Has been assessed under the management system of the certified organisation defined in the main certificate CN19/31787.00 as meeting the requirements of

ISO 45001:2018

For the following activities

Manufacture of Computer Products and Servers.

This certificate is valid from 28 October 2022 until 27 October 2025 and remains valid subject to satisfactory surveillance audits.
Issue 2.
The validity of this certificate depends on the validity of the main certificate.

Authorised by
Jonathan Hall
Global Head - Certification Services

SGS United Kingdom Ltd
Rossmore Business Park, Ellesmere Port, Cheshire, CH65 3EN, UK
t +44 (0)151 350-6666 - www.sgs.com

Lenovo (Singapore) Pte. Ltd.
151 Lorong Chuan,
#02-01, New Tech Park,
Singapore, 556741
(Tel - 65-6827-1000 & Fax- 65-6827-1100)

EU Declaration of Conformity

For the **ThinkPad E14 Gen 6 Notebook Computers**
Machine Type: 21M3, 21M4
Compliance ID: TP00148D, TP00148D(“*” can be 0-9, a-z, A-Z or blank)**

We, Lenovo (Singapore) Pte Ltd, declare under sole responsibility that the above products, manufactured for:

Lenovo PC HK Limited.
23/F, Lincoln House, Taikoo Place 979 King's Road,
Quarry Bay, Hong Kong, P.R.China

to which this declaration relates, is in conformity with the requirements of the following EU Directives:

- **Directive 2014/53/EU of the European Parliament and of the council on radio equipment.**
- **Directive 2009/125/EC establishing a framework for the setting of Ecodesign requirements for Energy-related products.**
- **Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment as amended by Directive 2015/863/EU.**

The conformity assessment procedure referred to in Article 17.4a of Directive 2014/53/EU has been followed and performed with the involvement of a Notified Body, in accordance with Article 3.2:

Notified Body Name/number: TIMCO Engineering, Inc./1177
Issued the EU-type examination certificate: E1177-243871

The Technical Documentation (TD), relevant to the product described above and which support this DoC is available from the EU contact address on this DoC.

Signed:_____ _____ Date:20 02 2024
Koh Ser Mein (Director)
Place of issue: Lenovo (Singapore) Pte Ltd.

European Contact for regulatory topics only:
Lenovo (Slovakia), Landererova 12, 811 09 Bratislava, Slovakia
Tel: +421 2 6868 3018

Lenovo (Singapore) Pte. Ltd.
151 Lorong Chuan,
#02-01, New Tech Park,
Singapore, 556741
(Tel - 65-6827-1000 & Fax- 65-6827-1100)

Standards References

The following harmonized standards and normative documents are those to which the product's conformance is declared, and by specific reference to the essential requirements of the referenced Directives:

RED											
Article 3.1a (Safety & Health)		EN 62368-1	:	2014 /A11:2017		✓					
		EN IEC 62368-1	:	2020 /A11:2020		✓					
		EN IEC 62311		2020		✓					
		EN 62479	:	2010							
		EN 50663	:	2017							
		EN 50665	:	2017							
		EN 50566	:	2017		✓					
		EN 62209-2	:	2010 + A1:2019		✓					
		EN IEC/IEEE 62209-1528	:	2021		✓					
Article 3.1b (EMC)		EN 55032	:	2015 + A11:2020		✓					
		EN 61000-3-2	:	2019 + A1:2021		✓					
		EN 61000-3-3	:	2013 + A2:2021		✓					
		EN 55035	:	2017 + A11:2020		✓					
		EN 301 489-1		V2.2.3	2019-11	✓					
		EN 301 489-3		V2.3.2	2023-01	✓					
		EN 301 489-17		V3.2.4	2020-09	✓					
		EN 301 489-19		V2.1.1	2019-04						
		EN 301 489-52		V1.2.1	2021-11						
						Wireless module inside					
						WLAN with Bluetooth 1	WLAN with Bluetooth 2	WLAN with Bluetooth 3	WLAN with Bluetooth 4		
Article 3.2 (Radio Spectrum)		EN 300 328		V2.2.2	2019-07	✓	✓	✓	✓		
		EN 301 893		V2.1.1	2017-05	✓	✓	✓	✓		
		EN 300 440		V2.1.1	2017-03	✓	✓	✓	✓		
		EN 300 440		V2.2.1	2018-07	✓	✓	✓	✓		
		EN 303 687		V1.1.1	2023-06	✓	✓				
		EN 301 908-1		V15.1.1	2021-09						
		EN 301 908-2		V13.1.1	2020-06						
		EN 301 908-13		V13.2.1	2022-02						
		EN 303 413		V1.2.1	2021-04						
		EN 300 330		V2.1.1	2017-02						
RoHS Directive		EN 50581:2012 EN IEC 63000:2018				✓					
ErP Directive		(EU) 2019/1782 (Lot 7)				✓					
		EC 1275/2008 (Lot 6/26) EN 50564:2011				✓					
		EC 617/2013 ErP – Class B EN 50564:2013 (Lot 3)									

European Contact for regulatory topics only:
Lenovo (Slovakia), Landererova 12, 811 09 Bratislava, Slovakia
Tel: +421 2 6868 3018

Lenovo (Singapore) Pte. Ltd.
151 Lorong Chuan,
#02-01, New Tech Park,
Singapore, 556741
(Tel - 65-6827-1000 & Fax- 65-6827-1100)

ANNEX

Wireless modules and External AC Adapters

Wireless module inside	MODEL
WLAN with Bluetooth 1	MT7922A22M
WLAN with Bluetooth 2	RTL8852CE
WLAN with Bluetooth 3	RTL8852BE
WLAN with Bluetooth 4	MT7921

Description	MODEL
External AC Adapter	ADLX65YDC2E
	ADLX65YLC2E
	ADLX65YCC2E
	ADLX65YAC2E
	ADLX65YDC3E
	ADLX65YLC3E
	ADLX65YCC3E
	ADLX65YAC3E

European Contact for regulatory topics only:
Lenovo (Slovakia), Landererova 12, 811 09 Bratislava, Slovakia
Tel: +421 2 6868 3018

THE ECO DECLARATION

ecma INTERNATIONAL

Annex B2 - Product environmental attributes
Computers and computer monitors

The declaration may be published only when all rows and/or fields marked with * are filled-in (N/A for not applicable). Additional information regarding each item may be found under P15.

Brand *	***Lenovo***	Logo
Company name *	***Lenovo***	
Contact information * e-mail address	***Lenovo Environmental Social and Governance environment@lenovo.com***	
Internet site *	***https://www.lenovo.com/us/en/sustainability-resources/***	
Additional information	***The latest version of this document can be found at: http://www.lenovo.com/ecodeclaration***	

The company declares (based on product specification or test results based obtained from sample testing), that the product conforms to the statements given in this declaration.	
Type of product *	***Notebook Computer***
Commercial name *	***ThinkPad E14 Gen 6 AMD***
Model number *	***21M3, 21M4***
Issue date *	***2024-03-01***
Intended market *	☒ **Global** ☐ **Europe** ☐ **Asia, Pacific & Japan** ☐ **Americas** ☐ **Other**
Additional information	***Energy Star8.0, EPEAT,TCO***

This is an uncontrolled copy when in printed form. Please refer to the contact information for the latest version.

About Annex B2
Annex B2 reflects Product environmental attributes relevant for Computers and Computer Monitors. The following items from the ECMA-370 Main body are not shown in the template:
P4.1 – P4.3 Consumable materials
P9.1 TEC and Print speed
P10.2 - P10.3 Chemical emissions from printing products
P11.1 - P11.3 Consumable materials for printing products.

Model number *	***21M3, 21M4***	**Logo**	Lenovo
Issue date *	***2024-03-01***		

Product environmental attributes - Legal requirements		**Requirement met**		
Item		Yes	No	N/A
P1	**Hazardous substances and preparations**			
P1.1*	Products comply with current European RoHS Directive. (See legal reference and NOTE B1)	☒	☐	
P1.2*	Products do not contain Asbestos (See legal reference) Comment: Legal reference has no maximum concentration value.	☒	☐	
P1.3*	Products do not contain Ozone Depleting Substances: Chlorofluorocarbons (CFC), hydrobromofluorocarbons (HBFC), hydrochlorofluorcarbons (HCFC), Halons, carbontetrachloride, 1,1,1-trichloroethane, methyl bromide (See legal reference). Comment: Legal reference has no maximum concentration values	☒	☐	
P1.4*	Products do not contain more than; 0,005% polychlorinated biphenyl (PCB), 0,005% polychlorinated terphenyl (PCT) in preparations (See legal reference)	☒	☐	
P1.5*	Products do not contain more than 0,1% short chain chloroparaffins (SCCP) with 10-13 carbon atoms in the chain containing at least 48% per mass of chlorine in the SCCP (See legal reference)	☒	☐	
P1.6*	Parts with direct and prolonged skin contact do not release nickel in concentrations above 0,5 $\mu g/cm^2$/week (See legal reference) Comment: Max limit in legal reference when tested according to EN1811:2011-5	☒	☐	☐
P1.7*	REACH Article 33 information about substances in articles is available at (add URL or mail contact): ***https://www.lenovo.com/us/en/Lenovo-REACH-SVHC-Disclosure***	☒	☐	☐
P2	**Batteries**			
P2.1*	If the product contains a battery or an accumulator, the battery/accumulator is labeled with the disposal symbol. Information on proper disposal is provided in user manual. (See legal reference)	☒	☐	☐
P2.2*	Batteries or accumulators do not contain more than 0,0005% of mercury or 0,002% of cadmium. (See legal reference)	☒	☐	☐
P2.3*	Batteries and accumulators are readily removable. (See legal reference)	☒	☐	☐
P2.4*	Documentation includes the number of cycles the (secondary) battery can withstand. (See legal reference)	☒	☐	☐
P2.5*	When internal batteries of a notebook computer cannot be “accessed and replaced by a nonprofessional user”, the related text is present and legible on the external packaging (See legal reference)	☒	☐	☐
P3	**Conformity verification & Eco design (ErP)**			
P3.1*	The product is CE-marked to show conformance with applicable legal requirements (see legal reference). The Declaration of Conformity can be requested at (add link or e-mail address): ***https://www.lenovo.com/us/en/compliance/eu-doc for EU*** ***https://www.lenovo.com/us/en/compliance/uk-doc for UK***	☒	☐	☐
P3.2*	The product complies with the applicable Eco design requirements for energy-related products, (See legal reference)	☒	☐	☐
	Required information is; ☒ given in item P15 or added to this document, ☒ available at (add URL): ***http://www.lenovo.com/ecodeclaration***	☒	☐	☐
P5	**Product packaging**			
P5.1*	Packaging and packaging components do not contain more than 0,01% lead, mercury, cadmium and hexavalent chromium by weight of these together	☒	☐	
P5.2*	The packaging materials are marked with abbreviations and numbers indicating the nature of the material(s) used (See legal reference)	☒	☐	☐
P5.3*	The product packaging material is free from ozone depleting substances as specified in the Montreal Protocol (See legal reference) Comment: Legal reference has no maximum concentration values	☒	☐	☐
P6	**Treatment information**			
P6.1*	Information for recyclers/treatment facilities is available (***https://lenovo.com/recycling***).	☒	☐	☐

NOTE B1 Restriction applies to the homogeneous material, unless other specified and expressed in weight %. Stating “Yes” means that the product is compliant with the mandatory requirements.

Model number *	***21M3, 21M4***	**Logo**	Lenovo
Issue date *	***2024-03-01***		

Product environmental attributes - Market requirements (See General NOTE GN below) **- Environmental conscious design**		**Requirement met**		
Item	*=mandatory to fill in. Additional information regarding each item may be found under P14.	Yes	No	N/A
P7	**Design** **Disassembly, recycling**			
P7.1*	Parts that have to be treated separately are easily separable	☒	☐	☐
P7.2*	Plastic materials in covers/housing have no surface coating	☐	☒	☐
P7.3*	Plastic parts > 100 g consist of one material or of easily separable materials	☒	☐	☐
P7.4*	Plastic parts > 25 g have material codes according to ISO 11469 referring ISO 1043-4	☒	☐	☐
P7.5	Plastic parts are free from metal inlays or have inlays that can be removed with commonly available tools	☒	☐	☐
P7.6*	Labels are easily separable (This requirement does not apply to safety/regulatory labels)	☒	☐	☐
	Product lifetime			
P7.7*	Upgrading can be done e.g. with processor, memory, cards or drives	☒	☐	☐
P7.8*	Upgrading can be done using commonly available tools	☒	☐	☐
P7.9	Spare parts are available after end of production for: ***5*** years			☐
P7.10	Service is available after end of production for: ***5*** years			☐
	Material and substance requirements			
P7.11*	Product cover/housing material type (e.g. plastics, metal, aluminum): Material type: ***PC+ABS*** Material type: ***Aluminium*** Material type: Material type: Material type: Material type: Material type: Material type: Material type:			
P7.12	Insulation materials of external electrical cables are PVC free	☐	☒	☐
P7.13	Insulation materials of internal electrical cables are PVC free	☒	☐	☐
P7.14	External plastic casing/cover parts > 25 g contain no more than 0,1% weight (1000 ppm) bromine and 0,1% weight (1000 ppm) chlorine attributable to brominated flame retardants, chlorinated flame retardants, and polyvinyl chloride or 0,3% weight (3000 ppm) bromine and 0,3% weight (3000 ppm) chlorine in parts containing more than 25% post-consumer recycled content	☒	☐	☐
P7.15	Printed circuit boards, PCBs (without components) are low halogen as defined in IEC 61249-2-21. (See NOTE B2): Only PCBs > 25g ☐ or All PCBs ☒	☒	☐	☐
P7.16	Flame retarded plastic parts > 25 g in covers / housings are marked according to ISO 1043-4: Marking: ***FR(40)***	☒	☐	☐
P7.17	Alt. 1: Chemical specifications of flame retardants in printed circuit boards > 25 g (without components): TBBPA (additive) ☐, TBBPA (reactive) ☐ (See NOTE B3), Other; chemical name: ***DOPO***, CAS #: ***35948-25-5***	☒	☐	☐
	Alt. 2: Chemical specifications of flame retardants in printed circuit boards (without components) > 25 g according to ISO 1043-4:	☐	☐	☐
P7.18	Alt. 1: Flame retarded plastic parts > 25 g contain the following flame retardant substances/preparations in concentrations above 0,1%: 1. Chemical name: , CAS #: (See NOTE B4) 2. Chemical name: , CAS #: " 3. Chemical name: , CAS #: "	☐	☐	☐
	Alt. 2: Chemical specifications of flame retardants in plastic parts > 25 g according to ISO 1043-4:***FR(40)***	☒	☐	☐
P7.19	In plastic parts > 25 g, flame retardant substances/preparations above 0,1% are used which have been assigned the following Risk phrases; and Hazard statements: ***H411, H413*** The source(s) for these classifications is/are found at (add URL(s)): , (See NOTE B5)	☒	☐	☐

GENERAL NOTE Standard references should direct to the latest version of a standard. If an older version of a standard is used, section P15 shall be used for explanation.

NOTE B2 IEC 61249-2-21 defines maximum limits of 900 ppm for each of the substances chlorine and bromine and a maximum limit of 1500ppm of these substances combined. The standard does not address fluorine, iodine and astatine which are included in the group of halogens.

NOTE B3 and B4 A Guidance document on Chemical substances is available; see http://www.ecma-international.org/publications/standards/Ecma-370.htm.

NOTE B5 If a certain substance has been assigned a certain risk phrases / hazard statement in the referenced source, this does not necessarily mean the substance has been tested for all of the hazards referred to by a certain customer.

Model number *	*21M3, 21M4*	Logo	Lenovo
Issue date *	*2024-03-01*		

Product environmental attributes - Market requirements (continued)		Requirement met		
Item		Yes	No	N/A
	Material and substance requirements (continued)			
P7.20*	Postconsumer recycled plastic material content is used in the product (See NOTE B6): If YES; at least one of the two alternatives below shall be answered; a) Of total plastic parts' weight > 25 g, the postconsumer recycled plastic material content (calculated as a percentage of total plastic by weight) is ***10.88*%**. or b) The weight of recycled material is ***33.7*** g	☒	☐	☐
P7.21*	Biobased plastic material content is used in the product (See NOTE B7): If YES; at least one of the two alternatives below shall be answered; a) Of total plastic parts' weight > 25 g, the biobased plastic material content (calculated as a percentage of total plastic by weight) is %. or b) The weight of the biobased plastic material is g	☐	☒	☐
P7.22*	Light sources are free from mercury, i.e. less than 0,1 mg/lamp If mercury is used specify: Number of lamps: and maximum mercury content per lamp: mg	☒	☐	☐
P7.23*	If product includes an integral display, the total mercury content in the integrated display: ***0.0*** mg	☐	☒	☐
P8	**Batteries**			
P8.1*	Battery chemical composition: ***LI-ION battery***			☐
P9	**Energy consumption (See NOTE B8)**			
P9.1	For the product the following power levels or energy consumptions are reported:			

Energy mode *		Power level at **100** V AC	Power level at **115** V AC	Power level at **230** V AC	Reference/Standard for energy modes and test method *	
Peak (On-Max)		***65*** W	***65*** W	***65*** W	***Full Load***	
Device Category 2						
Short Idle State – WOL Enabled (P_{short_idle})		***4.7340*** W	***4.5756*** W	***4.8204*** W	***ENERGY STAR Computers V8.0***	
Long Idle State – WOL Enabled (P_{long_idle})		***0.7272*** W	***0.7824*** W	***0.7824*** W	***ENERGY STAR Computers V8.0***	
Sleep (S3) – WOL Disabled (P_{Sleep})		***0.7272*** W	***0.7824*** W	***0.7824*** W	***ENERGY STAR Computers V8.0***	
Off Mode (S5) – WOL Disabled (P_{off})		***0.3984*** W	***0.3996*** W	***0.4344*** W	***ENERGY STAR Computers V8.0***	
PS No-load (External power supply / charger plugged in the wall outlet but disconnected from the product.)		***0.06*** W	***0.06*** W	***0.08*** W		☐
ETEC * Annual Energy Consumption	Cat 1:	kWh/year	kWh/year	kWh/year	Mode Weighting ***Full Capability***	
	Cat 2:	***14.4250*** kWh/year	***14.3226*** kWh/year	***14.9349*** kWh/year		☐
	Typical:	kWh/year	kWh/year	kWh/year		
External Power Supply Efficiency Level (International Efficiency Marking Protocol) * : ***VI***					***International Efficiency Marking Protocol* (IEMP) for *External Power Supplies***	☐
Display resolution * : ***3.136*** megapixels						☐
Default time to enter energy save mode: ***5*** minutes					***ENERGY STAR Computers V8.0***	☐
P9.2*	Information about the energy save function is provided with the product				☒ ☐	☐
P9.3	Energy efficiency class (monitors only):					☒

NOTE B6 Applies to a product containing plastic parts whose combined weight exceeds 100 g with the exception of printed circuit boards, cables, connectors and electronic components and bio-based plastic material.

NOTE B7 The following is to be excluded from the calculation of percentage: printed circuit boards, labels, cables, connectors and electronic components and postconsumer recycled plastic

NOTE B8 A Guidance document on Energy Efficiency is available;
see http://www.ecma-international.org/publications/standards/Ecma-370.htm.

Model number *	***21M3, 21M4***	**Logo**	Lenovo
Issue date *	***2024-03-01***		

Product environmental attributes - Market requirements (continued)				**Requirement met**		
Item				Yes	No	N/A
P10	**Emissions**					
	Noise emission – Declared according to ISO 9296 (See NOTE **B9**)					
P10.1	Mode	Mode description	Statistical upper limit A-weighted sound power level, $L_{WA,c}$ (B)			
	Idle	* ***Idle Mode***	* ***2.6***			☐
	Operation	* ***Operating (SSD/HDD)*** * ***Operating (CPU)***	* ***NA*** * ***3.4***			☐
	Other Mode	***Declared A-weighted sound pressure level (dB)***	***14.9 (operator position – idle)***			
	Other mode	***Declared A-weighted sound pressure level (dB)***	***NA (operator position – operating-HDD/SSD)*** ***22.7 (operator position – operating-CPU)***			
	Measured according to: ☒ ISO 7779 ☐ ECMA-74 ☐ Other (only if not covered by ECMA-74)					
	Electromagnetic emissions					
P10.4	Computer display meets the requirement for low frequency electromagnetic fields of the following voluntary program(s): ***MPR-II(3 pin AC adapter only)***			☒	☐	☐
P12	**Ergonomics for computing products**					
P12.1*	The display meets the ergonomic requirements of ISO 9241-307 for visual display technologies			☐	☒	☐
P12.2*	The physical input device meets the requirements of ISO 9995 and ISO 9241-410			☐	☒	☐
P13	**Packaging and documentation**					
P13.1*	Product packaging material type(s): ***Corrugated single wall*** weight (kg): ***0.420*** Product packaging material type(s): ***Bamboo molded pulp*** weight (kg): ***0.088*** Product packaging material type(s): ***from offset / recycled source*** weight (kg): ***0.0077*** Product packaging material type(s): weight (kg): Product packaging material type(s): weight (kg): Product packaging material type(s): weight (kg): Product packaging material type(s): weight (kg):					
P13.2*	Product plastic primary packaging is free from PVC			☒	☐	☐
P13.3*	For product primary corrugated fiberboard packaging, specify the contained percentage of minimum post-consumer recovered fiber content: ***80*** %					☐
P13.4*	Specify media for user and product documentation (tick box): Electronic ☒, Paper ☒, Other ☐					☐
P13.5	(Please only complete this item if paper documentation used) User and product documentation on paper media is chlorine-free: If Yes, please specify: Totally chlorine-free Elemental chlorine-free Processed chlorine-free			☒ ☒ ☒ ☐	☐	
P14	**Voluntary programs**					
P14.1	The product meets the requirements of the following voluntary program(s): Choose ESTAR Compliance Criteria version: ***8.0*** Date: Product category: ***2*** Eco-label: ***EPEAT*** Criteria version: ***1680.1-2018*** Date: Product category: ***Notebook*** Eco-label: ***TCO*** Criteria version: ***9.0*** Date: Product category: ***Notebook***					
P15	**Additional information (See NOTE B10)**					
P9	***Energy consumption of computer products; description of the tested product configuration:***					
P7.7 ***P7.8***	***In further explanation of Upgradability (P7.7/P7.8), the following components can be upgraded:*** ***Processor*** ***Upgradeable with special tools*** ***Memory*** ***Upgradeable using common tools*** ***Cards*** ***Upgradeable using common tools*** ***Drives/Storage*** ***Upgradeable using common tools***					
	NOTE: Supplier makes no representations, guarantees, assurances or warranties whether express or implied, regarding the information contained in this document. All information provided by supplier in this document is provided based on supplier's knowledge available at the time of completion, and supplier shall have no obligation to update such information. The information provided here is approximate and provided for informational purposes only. See a Lenovo Account Representative for more information.					

NOTE B9 A Guidance document on Acoustic Noise is available; see http://www.ecma-international.org/publications/standards/Ecma-370.htm.

NOTE B10 Additional lines may be inserted to declare further items, by positioning the cursor at the far right of the row and hitting the <Enter> key.

Legal references Europe Annex B2

Reference	Declaration item
Directive 2011/65/EU (RoHS Directive)* * Specific exemptions apply for certain products and applications.	P1.1, P3.1
Regulation (EC) 1907/2006 (REACH Regulation), annex XVII	P1.2, P1.4, P1.6, P1.7
Regulation (EC) 2037/2000, 2038/2000, 2039/2000 (Marketing and use of Ozone layer depleting substances)	P1.3, P5.3
Norwegian regulation relating to restrictions on the use of certain dangerous chemicals 20.12.2002	P1.5
Directive 2006/66/EC (Battery and accumulators Directive), as amended.* * These provisions shall not apply where, for safety, performance, medical or data integrity reasons, continuity of power supply is necessary and requires a permanent connection between the appliance and the battery or accumulator.	P2.1, P2.2, P2.3, P8.1
Directive 2014/35/EU (Low Voltage Directive)	P3.1
Directive 2014/30/EU (EMC Directive)	P3.1
Directive 2014/53/EU (RE Directive)	P3.1
Regulation (EC) 801/2013 amending Regulation (EC) No 1275/2008 with regard to ecodesign requirements for standby, off mode electric power consumption of electrical and electronic household and office equipment, and amending Regulation (EC) No 642/2009 with regard to ecodesign requirements for televisions	P3.1, P3.2
Commission Regulation (EC) No 278/2009 of 6 April 2009 implementing Directive 2005/32/EC of the European Parliament and of the Council with regard to ecodesign requirements for no-load condition electric power demand and average active efficiency of external power supplies	P3.1, P3.2, P9.1
COMMISSION REGULATION (EU) No 617/2013 of 26 June 2013 implementing Directive 2009/125/EC of the European Parliament and of the Council with regard to ecodesign requirements for computers and computer servers	P2.4, P2.5, P3.1, P3.2, P7.23, P9.1
Regulation（EC）No 1272/2008 (CLP Regulation)	P7.19
Directive 2004/12/EC (Packaging Directive)	P5.1
Decision 97/129/EC (Secondary packaging legislation)	P5.2
Directive 2012/19/EU (WEEE directive) Implementing Regulation (EU) 2019/290 establishing the format for registration and reporting of producers of electrical and electronic equipment to the register. Commission Implementing Regulation 2017/699 establishing a common methodology for the calculation of the weight of electrical and electronic equipment (EEE) placed on the national market in each Member State and a common methodology for the calculation of the quantity of waste electrical and electronic equipment (WEEE) generated by weight in each Member State.	P6.1

Lenovo ErP Lot26 Information Sheet
- Network Equipment -

As required by_

- Commission Regulation (EC) No 1275/2008 of 17 December 2008 implementing Directive 2005/32/EC of the European Parliament and of the Council with regard to ecodesign requirements for standby and off-mode electric power consumption of electrical and electronic household equipment (ErP Lot 6)
- Commission Regulation (EU) No 801/2013 of 22 August 2013 implementing Directive 2009/125/EC of the European Parliament and of the Council with regard to ecodesign requirements for (ErP Lot 26).

Products scope of this sheet:
Notebook/Tablet Computer < 6 W Idle

This document is only valid in connection with the IT Eco Declaration of the specific Product.

Commercial name	***ThinkPad E14 Gen 6 AMD***	**Logo**
Model Number	***21M3, 21M4***	
Product Type	***Notebook Computer with Idle Power <6W***	
Issue Date	***2024-03-01***	
Additional information		

P7.1.1 Product environmental attributes

(1) year of manufacture: ***2024***

Product uses a low voltage external power supply. Only Section (5) is completed. ☐

(2)

Network Standby Classification	***LoNA Equipment***
Off Mode Power (Watts)	***0.4 Watts***
Standby Mode	***Watts*** ☒Mode Not Applicable ***minutes Default Delay Time***
Description of how to enable Network Standby Mode	***Network Standby Mode is enable at shipment***
Description of how to manually enter Network Standby Mode	***1) Click on the Power Button and choose Sleep*** ***2) Press the Power Button once***
Default Delay time to Network Standby Mode	***5.0 minutes***
Reactivation Function from Network Standby Mode	***Open Notebook, Press Keyboard or power button***

(3)

Network Port	Wired Ethernet	Wireless Ethernet	USB-A	USB-C	HDMI	BlueTooth	Other:
Present in Product	☒	☒	☒	☒	☒	☒	☒
Activated at Shipment	☒	☒	☒	☒	☒	☐	☐
Active in Network Standby Mode	☒	☒	☐	☐	☐	☒	☐
Location of Network Port	*Right*	*N/A*	*Right*	*Left*	*Left*	*N/A*	*Left*
Network Port Maximum Performance	*0.125 GB/s*	*0.2 GB/s*	*0.63 GB/s*	*1.2 GB/s*	*6.0 GB/s*	*0.000360 GB/s*	*0.6 GB/s*
Network Protocol	*IEEE 802.3*	*Wi-Fi 6E; 802.11ax*	*USB 3.2*	*Type C 3.2*	*HDMI 2.1*	*BT 5.0*	*USB 3.2*
Network Standby Mode Power	*0.7 Watts*	*0.7 Watts*	*Watts*	*Watts*	*Watts*	*0.7 Watts*	*Watts*
Network Standby Power – All Connections	*0.7 Watts*						

Additional Information

Instructions on activating and deactivating wireless network(s) is included in the User Manual

(4) Test parameters for measurements,

ambient temperature	*23 degrees Celsius*
test voltage in V and frequency in Hz	*230 V / 50 Hz*
total harmonic distortion of the electricity supply system	*2.00%*
information and documentation on the instrumentation, set-up and circuits used for electrical testing	

Equipment	Make/Model	Last Calibration Date
AC Source	*Chroma 61601*	*23/07/04*
Power Analyzer	*Chroma 66205*	*23/09/08*
Timer	*Chroma 66205*	*23/09/08*
Thermometer	*AS106A*	*23/07/08*
Hygrometer	*AS106A*	*2023/07/08*

(5) External power supply efficiency (if applicable)*:

Model	Output Voltage	Output Current	Output Power	Average Active Efficiency	10% Load Efficiency	No Load Power
ADLX65UAGE2A	*20* V	*3.25* A	*65* W	*91.70%*	*88.47%*	*0.04* W
ADLX65UCGE2A	*20* V	*3.25* A	*65* W	*91.09%*	*89.13%*	*0.01* W
ADLX65UDGE2A	*20* V	*3.25* A	*65* W	*91.49%*	*86.22%*	*0.06* W
ADLX65ULGE2A	*20* V	*3.25* A	*65* W	*90.15%*	*83.55%*	*0.07* W
ADLX65YCC3E	*20* V	*3.25* A	*65* W	*91.85%*	*86.70%*	*0.07* W
ADLX65YLC3E	*20* V	*3.25* A	*65* W	*90.29%*	*86.21%*	*0.08* W
ADLX65YAC3E	*20* V	*3.25* A	*65* W	*90.00%*	*84.08%*	*0.06* W
ADLX65YDC3E	*20* V	*3.25* A	*65* W	*91.26%*	*85.72%*	*0.06* W
ADLX65YCC2E	*20* V	*3.25* A	*65* W	*91.85%*	*86.70%*	*0.07* W
ADLX65YLC2E	*20* V	*3.25* A	*65* W	*90.29%*	*86.21%*	*0.08* W
ADLX65YAC2E	*20* V	*3.25* A	*65* W	*90.00%*	*84.08%*	*0.06* W
ADLX65YDC2E	*20* V	*3.25* A	*65* W	*91.26%*	*85.72%*	*0.06* W
	V	A	W			W
	V	A	W			W

*Values are tested at 230V / 50Hz

(6) Measurement methodology used to determine information mentioned in points (5) – external PSU efficiency:
EN 50563:2011/A1:2013

Additional information